

08-21-2000

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Patent and Trademark Office



101438183

To the Honorable Commissioner of Patents and Trademarks: Please record the attached original documents or copy thereof

1. Name of Conveying Part(ies):

Chih-Chen Cho  
Richard H. Lane  
Charles H. Dennison

7-21-00

Additional name(s) of conveying party(ies) attached?

☐ Yes ☒ No

2. Name and address of receiving party(ies):

Name: Micron Technology, Inc.

Internal Address: \_\_\_\_\_

Street Address: 8000 South Federal Way

City: Boise State: ID Zip: 83716

3. Nature of conveyance:

- ☒ Assignment ☐ Security Agreement  
☐ Merger ☐ Change of Name  
☐ Other \_\_\_\_\_

Execution Date: 2/29/00, 3/1/00 and 6/24/00

Additional names(s) & address(es) attached: ☐ Yes ☒ No

4. Application number(s) or patent number(s):

If this document is being filed together with a new application, the execution date of the application is:

A. Patent Application No.(s):

B. Patent No.(s)

Additional numbers attached: ☐ Yes ☒ No

Additional numbers attached: ☐ Yes ☒ No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: David G. Latwesen, Ph.D.

Internal Address: Wells, St. John, Roberts,

Gregory & Matkin P.S.

Street Address: 601 W. First Avenue, Ste. 1300

City: Spokane State: WA Zip: 99201-3828

6. Total number of applications and patents involved: 1

7. Total fee (37 CFR 3.41). . . . . \$ 40

☒ Enclosed  
☐ Authorized to be charged to deposit account

8. Deposit account number  
23-0925

(Attach duplicate copy of this page if paying by deposit account)

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9. Statement and Signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

David G. Latwesen, Ph.D.  
Name of Person Signing

[Signature]  
Signature

7/1/00  
Date

TOTAL NUMBER OF PAGES INCLUDING COVER SHEET, ATTACHMENTS AND DOCUMENT: 6

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**ASSIGNMENT**

**PARTIES TO THE ASSIGNMENT:**

**INVENTORS:**

Chih-Chen Cho  
Richard H. Lane  
Charles H. Dennison

**ASSIGNEE:**

Micron Technology, Inc.  
Corporation of the State of Delaware  
8000 South Federal Way  
Boise, Idaho 83706-9632

**BACKGROUND OF THIS ASSIGNMENT:**

INVENTORS have conceived certain new and useful inventions disclosed in a United States patent application titled Methods of Forming Portions of Transistor Structures, Methods of Forming Array and Peripheral Circuitry, and Structures Comprising Transistor Gates.

MICRON TECHNOLOGY, INC. (hereinafter referred to as "ASSIGNEE") desires to acquire the entire right, title and interest in said inventions and with respect to any Letters Patent that may be granted with respect to the inventions in both the United States and in all foreign countries.

**THE PARTIES AGREE AS FOLLOWS:**

In consideration of good and valuable consideration, the receipt sufficiency and adequacy of which is hereby acknowledged, INVENTORS hereby sell, assign and transfer to ASSIGNEE the entire right, title and

1 interest in the above-identified application executed currently with this  
2 assignment and to any reissues, renewals, divisions or continuations thereof,  
3 and hereby authorizes the Commissioner of Patents and Trademarks to issue  
4 such Letters Patent to ASSIGNEE for the sole use of ASSIGNEE, its  
5 successors or assigns.

6 INVENTORS further agree to execute, at the request and expense of  
7 ASSIGNEE such other formal documents as may be required to fully convey  
8 the interest transferred herein and will similarly execute any application papers  
9 required for the filing of any division, continuation, renewal or reissue of the  
10 patent application or resulting Letters Patent; and will generally do everything  
11 necessary or desirable to obtain and enforce proper protection for the  
12 inventions assigned hereby.

13 INVENTORS further assign to ASSIGNEE the whole right, title and  
14 interest in the inventions disclosed in the application throughout all countries  
15 foreign to the United States. ASSIGNEE is hereby authorized to apply for  
16 patents relating to the inventions in its own name in countries where such  
17 procedure is proper; to claim the benefit of the International Convention; to  
18 file and prosecute International Applications relating to the inventions under  
19 the Patent Cooperation Treaty; and to file and prosecute applications relating  
20 to the inventions under the European Patent Convention. INVENTORS agree  
21 to execute applications relating to the inventions in those countries and under  
22 those conventions where it is necessary that the same be executed by the  
23 inventor, and to execute assignments of such applications and the resulting

1 Letters Patent to ASSIGNEE as well as all other necessary papers in relation  
2 to such applications and Letters Patent.

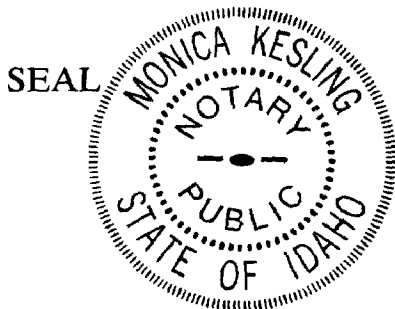
3 INVENTORS further warrant and covenant that no assignment, grant,  
4 mortgage, license or other agreement affecting the rights and property herein  
5 conveyed has been or will be made to others by the undersigned, and that the  
6 full rights to convey the same as herein expressed is possessed by the  
7 undersigned.

8 To be binding on the heirs, assigns, representatives and successors of  
9 the undersigned and extend to the successors, assigns and nominees of the  
10 Assignees.

11 (Signature) Chih-Chen Cho Date: March 1, 2000  
12 ChihChen Cho

13 State of Idaho )  
14 County of Ada ) ss.

15 BEFORE ME, this 1<sup>st</sup> day of March 2000 personally appeared  
16 the above-named inventor, to me known to be the person who is described in  
17 and who executed the foregoing assignment instrument and acknowledged to  
18 me that he/she executed the same of his/her own free will for the purpose  
19 therein expressed.



Monica Kesling  
Notary or Consular Officer  
My Commission Expires: 5-17-03

1 (Signature)

Richard H. Lane

Date: 2/29/00

2  
3 State of

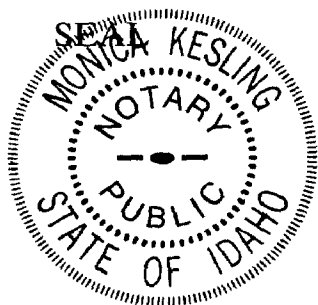
Idaho

) ss.

4 County of

Ada

5 BEFORE ME, this 29 day of February 2000 personally appeared  
6 the above-named inventor, to me known to be the person who is described in  
7 and who executed the foregoing assignment instrument and acknowledged to  
8 me that he/she executed the same of his/her own free will for the purpose  
9 therein expressed.



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Monica Kesling

Notary or Consular Officer

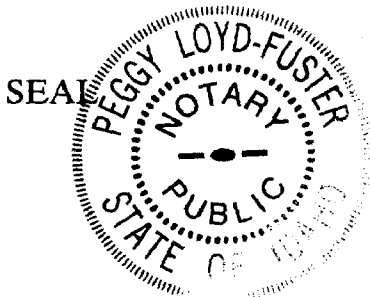
My Commission Expires:

5-17-03

1 (Signature) Charles H. Dennison Date: 6-24-01  
Charles H. Dennison

2  
3 State of Idaho )  
4 County of Ada ) ss.  
5 )

6 BEFORE ME, this 24 day of June, 2000 personally appeared  
7 the above-named inventor, to me known to be the person who is described in  
8 and who executed the foregoing assignment instrument and acknowledged to  
9 me that he/she executed the same of his/her own free will for the purpose  
10 therein expressed.



Peggy Loyd-Fuster  
Notary or Consular Officer  
My Commission Expires: 4-1-2003